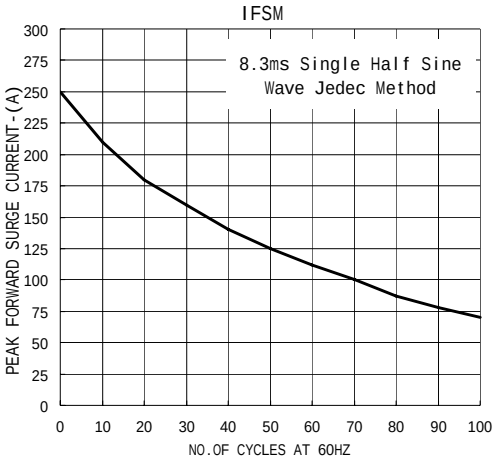
WR0596 ṂṂ Ꝉ ⁼ ᵍ‿ ‖ ㄱ
Schottky Barrier Diode in a TO-263 Plastic Package.

Ꮋ* ᵇ ʁ ᴗ ı Ꮋ ı ă ı ѽ ' ⱨ
Low forward voltage drop,low power losses,High efficiency operation.

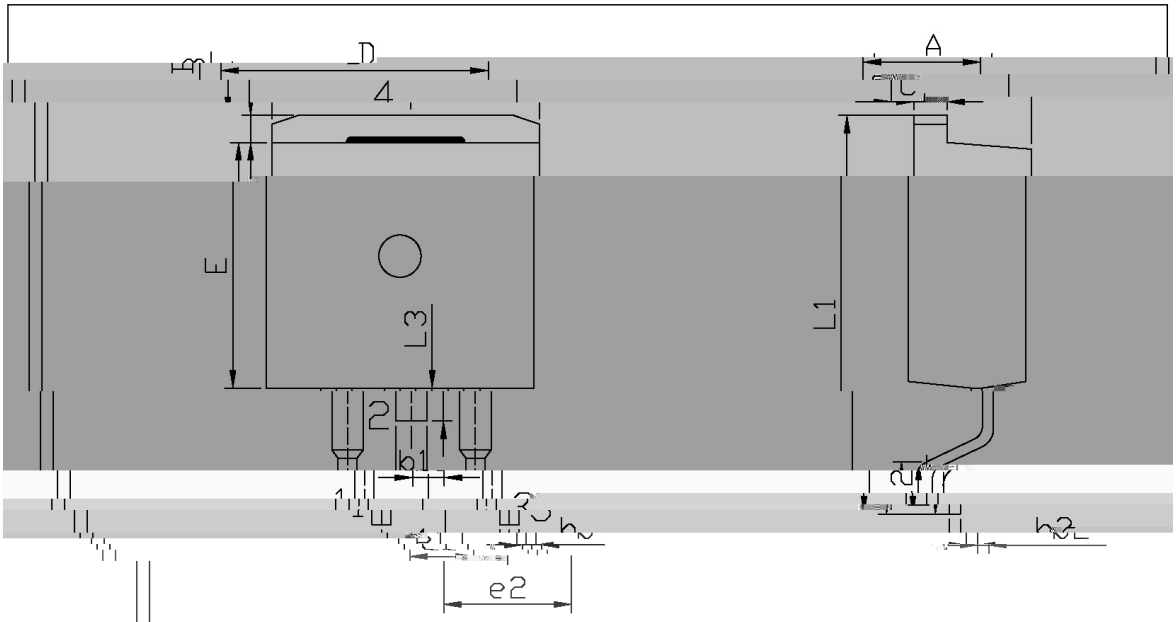
ᵹ ⱨ ļ ' ڜ Ψ ʰ ı Ầ ʜ ɔ ◊ ı ㅅ ㅣ‾ ‖ ㄱ ı RU0lqj ‾ ‖ ㄱ ı GF0GF ᶎ Ω ʰ ⊐ ɔ – ɾ ᵇ Ȝ ǐ
For use in high frequency inverters, switching power supplies, freewheeling diodes, OR-ing diode, dc-to-dc converters and re

v ̈Ω	ϒ N	̈Ω Ë	D Ɥ
Parameter	Symbol	Rating	

/ Electrical Characteristic Curve

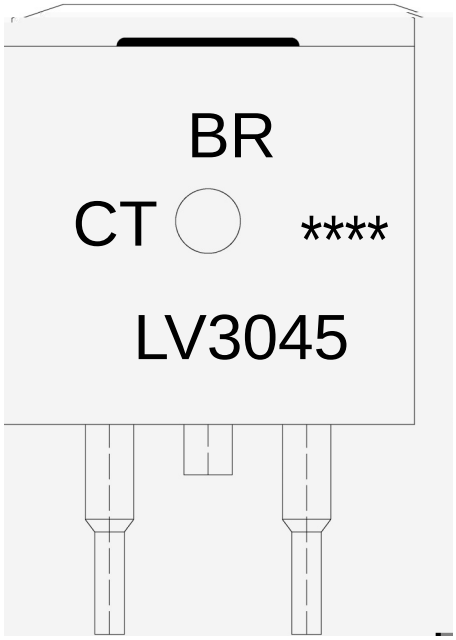


/ Package Dimensions



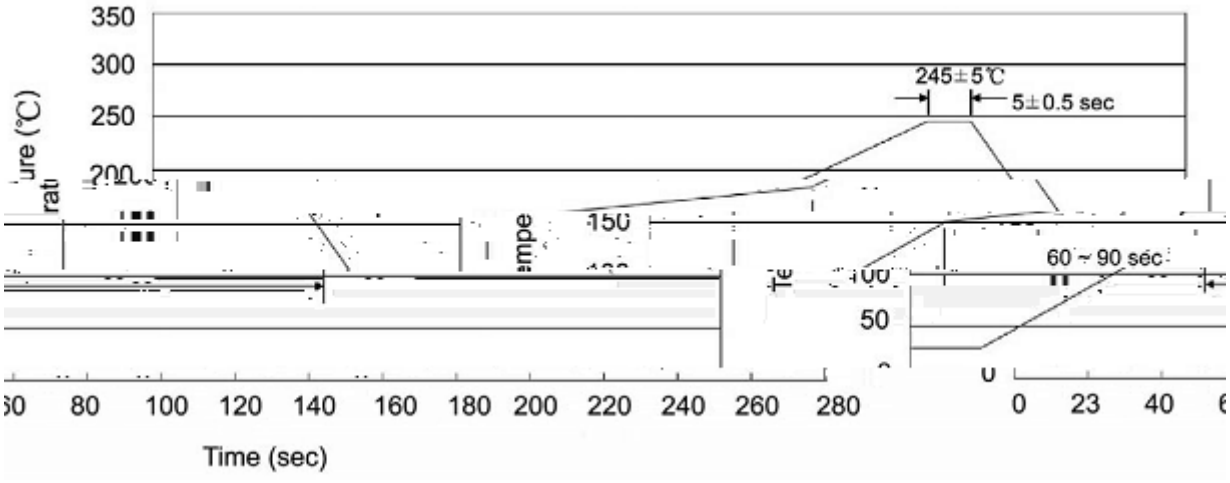
Dimensions In Millimeters					
Symbol	Min	Max	Symbol	Min	Max
A	4.30	4.70	E	9.00	9.40
b	1.00	1.40	e1	2.34	2.74

/ Marking Instructions



ͻ ˝ χ	
EU χ	ѭ ϗ ᴎ Ր
0Y6378 χ	ѭ ғ β ȝ ᴺ
FW=	ѭ ɲ ԉ ᒧ ⚌
---- χ	ѭ ɨ ғ ή ᴺ Ր ɪ ȼ ɨ ғ ή ᴺ Ψ ק
Note:	
BR:	Company Code
0Y6378 χ	Product Type.
FW:	Internal Structure
****:	Lot No. Code, code change with Lot No.

( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)



ㄴ ˝ χ

1 Ĺ ♬ □ ỷ 25 Ḱ 150 ɬ ı ˋH ڑ 60 Ḱ 90sec;

2 Š Ö □ ỷ 245 ° 5 ɬ ı ˋH ڑ ˋY ㅅ ㎛ 5 ° 0.5sec;

3 ì ˙ ㅣ ˛ ɔ ෯ ỷ ㎛ 2 Ḱ 10 ɬ /sec.

Note:

1.Preheating:25~150 ɬ , Time:60~90sec.

2.Peak Temp.:245 ° 5 ɬ , Duration:5 ° 0.5sec.

3. Cooling Speed: 2~10 ɬ /sec.

/ Resistance to Soldering Heat Test Conditions

□ ỷ χ 260 ° 5 ɬ ˋH ڑ χ 10 ° 1 sec. Temp.:260±5 Time:10±1 sec

/ Packaging SPEC.

ɔ ` ㅛ Ł / REEL

Package Type	Units					Dimension (unit mm^3)		
	Units/Reel /	Reels/Inner Box /	Units/Inner Box /	Inner Boxes/Outer Box /	Units/Outer Box /	Reel	Inner Box	Outer Box
TO-263	800	1	800	5	4,000	13 ×24	360×360×50	385×257×392